

IN THE CLAIMS

Please amend the claims as follows:

1. (Previously Presented) A device comprising:
a substrate, further including:
a first major surface including a plurality of lands; and
a second major surface;
at least one component attached to at least some of the plurality of lands on the first major surface, the at least one component having a first height with respect to the first major surface; and
at least one sacrificial component attached to the first major surface, the at least one sacrificial component having a second height with respect to the first major surface, the second height greater than the first height, the at least one sacrificial component further including a fuse.
2. (Original) The device of claim 1 wherein at least one sacrificial component includes at least one solder contact.
3. (Original) The device of claim 1 wherein at least one sacrificial component includes at least two solder contacts.
4. (Original) The device of claim 3 wherein the fuse is positioned between the at least two solder contacts.
5. (Original) The device of claim 3 wherein the sacrificial component further comprises a body, the body further comprising:
a first body surface that includes the at least two solder contacts of the sacrificial component;
a second body surface substantially parallel with the first body surface devoid of a conductor.

6. (Original) The device of claim 1 wherein the device includes a semiconductor.
7. (Original) The device of claim 1 wherein the device includes a ball grid array semiconductor device.
8. (Original) The device of claim 1 wherein the at least one sacrificial component further comprises:
 - a body; and
 - a C-shaped conductor including a portion of which is embedded within the body.
9. (Original) The device of claim 8 wherein the C-shaped conductor includes a fuse, wherein the fuse is molded within the at least one body of the sacrificial component.
10. (Original) The device of claim 8 wherein the body is an insulative material.
11. (Canceled)
12. (Currently Amended) ~~The assembly of claim 11~~ An assembly comprising:
a ball grid array device, further including:
 - a first major surface including an array of lands;
 - a second major surface; and
 - an array of solder balls attached to a first portion of the array of lands;
 - at least one discrete component attached to a second portion of the array of lands; and
 - at least one sacrificial component attached to a third portion of the array of lands, the sacrificial component having a fuse therein, wherein the at least one discrete component has a first height, and the at least one sacrificial component has a second height greater than the first height.

13. (Currently Amended) ~~The assembly of claim 11~~ An assembly comprising:
a ball grid array device, further including:
a first major surface including an array of lands;
a second major surface; and
an array of solder balls attached to a first portion of the array of lands;
at least one discrete component attached to a second portion of the array of lands; and
at least one sacrificial component attached to a third portion of the array of lands, the
sacrificial component having a fuse therein, wherein the at least one non sacrificial component is
positioned to prevent the at least one discrete component from impacting another surface.

14. (Currently Amended) ~~The assembly of claim 11 further~~ An assembly comprising:
a ball grid array device, further including:
a first major surface including an array of lands;
a second major surface; and
an array of solder balls attached to a first portion of the array of lands;
at least one discrete component attached to a second portion of the array of lands;
at least one sacrificial component attached to a third portion of the array of lands, the sacrificial
component having a fuse therein; and
a printed circuit board, wherein the ball grid array device is attached to the printed circuit
board, the at least one sacrificial component is positioned with respect to the printed circuit board
to prevent the at least one discrete component from contacting the printed circuit board.

15. (Currently Amended) ~~The assembly of claim 11 further~~ An assembly comprising:
a ball grid array device, further including:
a first major surface including an array of lands;
a second major surface; and
an array of solder balls attached to a first portion of the array of lands;
at least one discrete component attached to a second portion of the array of lands;
at least one sacrificial component attached to a third portion of the array of lands, the sacrificial
component having a fuse therein; and

a printed circuit board, wherein the ball grid array device is attached to the printed circuit board, the printed circuit board further comprising:

a ground plane; and

a power plane, wherein the at least one non operational, sacrificial component is formed of an insulative material and positioned with respect to the printed circuit board to prevent the at least one discrete component from contacting the ground plane and the power plane of the printed circuit board.

16.-23. Canceled.

24. (Original) ~~The assembly of claim 22~~ An assembly comprising:

a ball grid array device, further including:

a first major surface including an array of lands;

a second major surface; and

an array of solder balls attached to a first portion of the array of lands;

at least one discrete component attached to a second portion of the array of lands; and

a plurality of non operational, sacrificial components attached to a third portion of the array of lands, wherein the least one discrete component has a first height, and the plurality of non operational, sacrificial components attached to a third portion of the array of lands pads have a second height that is greater than the first height.

25.-35. Canceled.